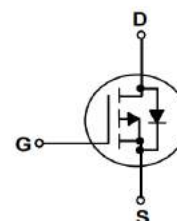


Features

- P-Channel
- Green Device Available
- Low Gate Charge
- 100% EAS Tested

V_{DS}	-40	V
$R_{DS(on),TYP@ V_{GS}=-10V}$	6.2	m Ω
$R_{DS(on),TYP@ V_{GS}=-4.5V}$	8	m Ω
I_D	-80	A

TO-252



Part ID	Package Type	Marking	Packing
ZT080P04D	TO-252	ZT080P04D	2500pcs/reel

Absolute Maximum Ratings $T_A=25^{\circ}\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings ($T_C=25^{\circ}\text{C}$ Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	± 20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-40	V	
T_J	Maximum Junction Temperature	150	$^{\circ}\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$	
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_C=25^{\circ}\text{C}$ -320	A	
Mounted on Large Heat Sink				
I_D	Drain Current-Continuous	$T_C=25^{\circ}\text{C}$	-80	A
		$T_C=100^{\circ}\text{C}$	-50.6	A
P_D	Maximum Power Dissipation	$T_C=25^{\circ}\text{C}$	81.16	W
$R_{\theta JA}$	Thermal Resistance from Junction-to-Ambient (Note 3)		54	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case		1.9	$^{\circ}\text{C}/\text{W}$
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed (Note 2)		101.25	mJ

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J=25°C (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-40	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-40V, V _{GS} =0V	--	--	-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1.0	-1.6	-2.0	V
R _{DS(on)}	Drain-Source On-State Resistance (Note 4)	V _{GS} =-10V, I _D =-20A	--	6.2	8	mΩ
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-15A	--	8	11	mΩ
g _{FS}	Forward Transconductance (Note 4)	V _{DS} =-10V, I _D =-20A	--	104	--	S
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated) (Note 5)						
C _{iss}	Input Capacitance	V _{DS} =-20V, V _{GS} =0V, f=1MHz	--	5293	--	pF
C _{oss}	Output Capacitance		--	429	--	pF
C _{rss}	Reverse Transfer Capacitance		--	386	--	pF
R _g	Gate Resistance	f=1MHz	--	4.2	--	Ω
Q _g	Total Gate Charge	V _{DS} =-20V, I _D =-20A, V _{GS} =-10V	--	109	--	nC
Q _{gs}	Gate-Source Charge		--	12.3	--	nC
Q _{gd}	Gate-Drain Charge		--	23	--	nC
Switching Characteristics (Note 5)						
T _{d(on)}	Turn-on Delay Time	V _{DD} =-20V, I _D =-20A, R _G =3Ω, V _{GS} =-10V	--	16.5	--	ns
T _r	Turn-on Rise Time		--	10	--	ns
T _{d(off)}	Turn-Off Delay Time		--	64	--	ns
T _f	Turn-Off Fall Time		--	17	--	ns
Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated)						
I _{SD}	Source-Drain Current (Body Diode)		--	--	-80	A
V _{SD}	Forward on voltage (Note 4)	I _S =-20A, V _{GS} =0V	--	--	-1.2	V
T _{rr}	Reverse Recovery Time	T _J =25°C, I _F =-20A, V _{GS} =0V	--	42	--	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs	--	29	--	nC

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The EAS data shows Max. rating . The test condition is V_{DD}= -30V, V_{GS}= -10V, L= 0.1mH, I_{AS}= -45A.
3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

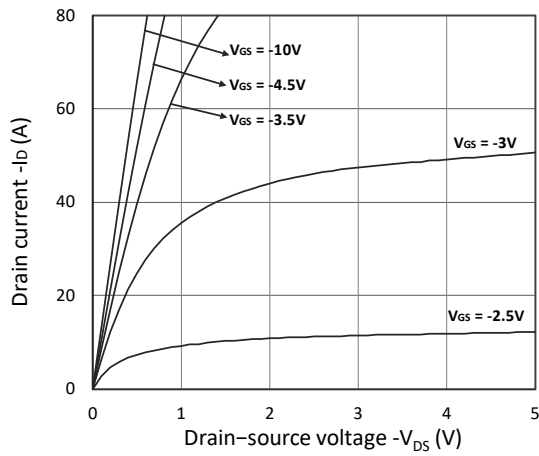


Figure 1. Output Characteristics

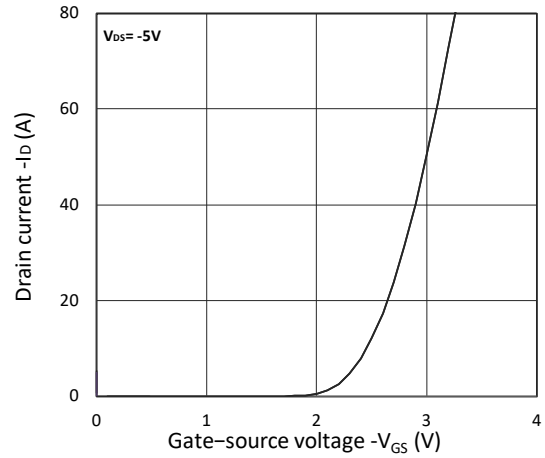


Figure 4. Transfer Characteristics

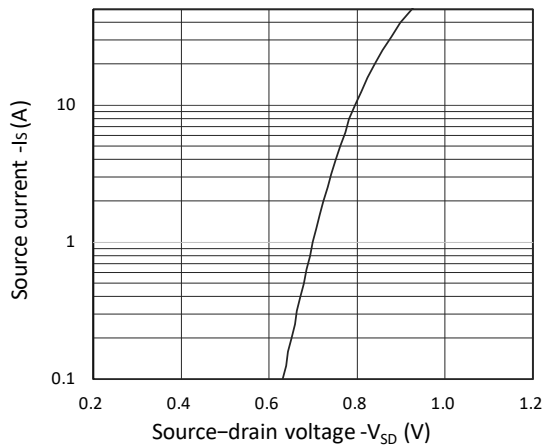


Figure 2. Forward Characteristics of Reverse

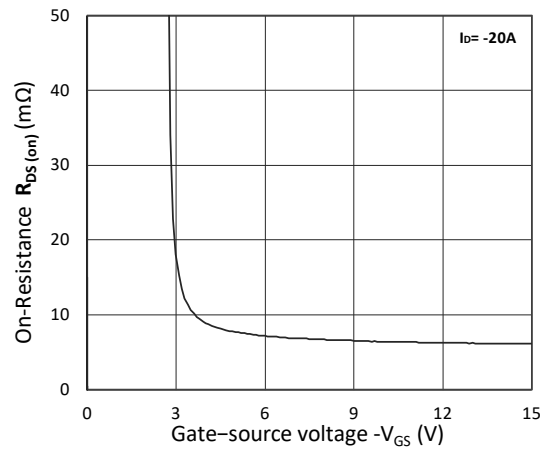


Figure 5. $R_{DS(ON)}$ vs. V_{GS}

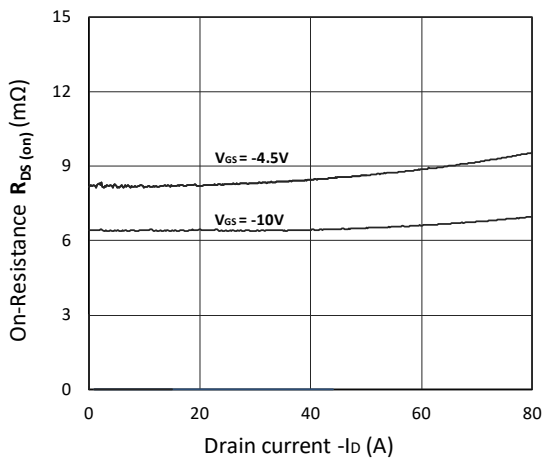


Figure 3. $R_{DS(ON)}$ vs. I_D

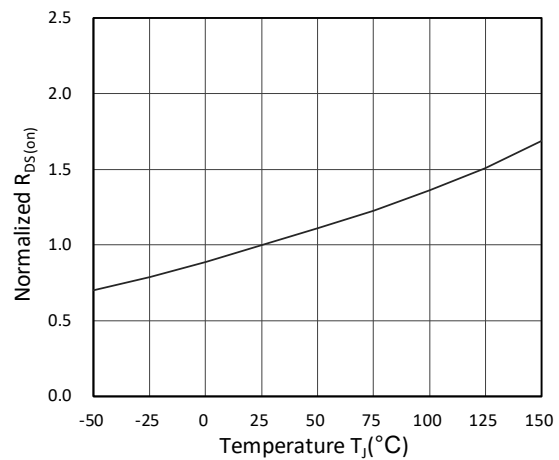


Figure 6. Normalized $R_{DS(ON)}$ vs. Temperature

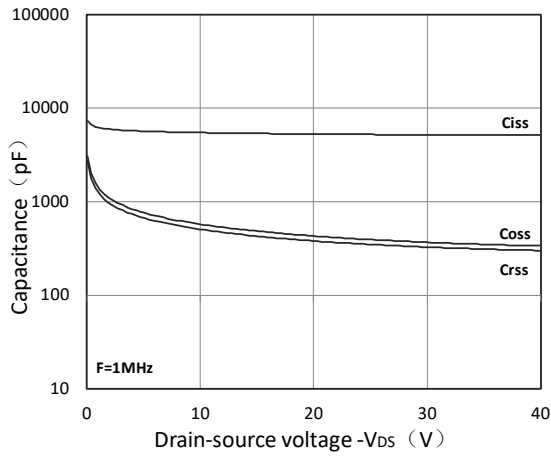


Figure 7. Capacitance Characteristics

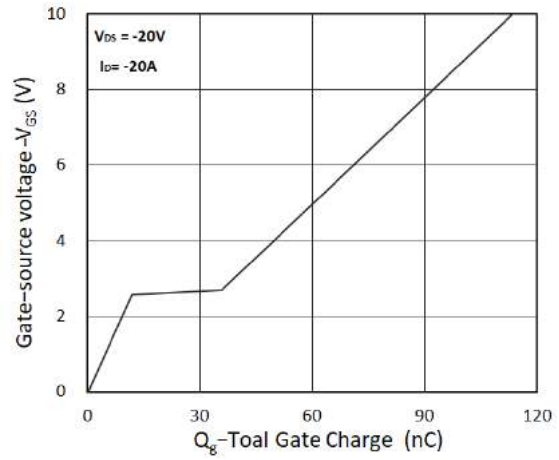


Figure 9. Gate Charge Characteristics

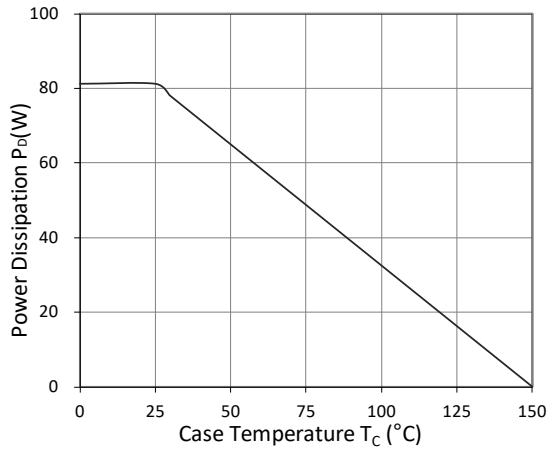


Figure 8. Power Dissipation

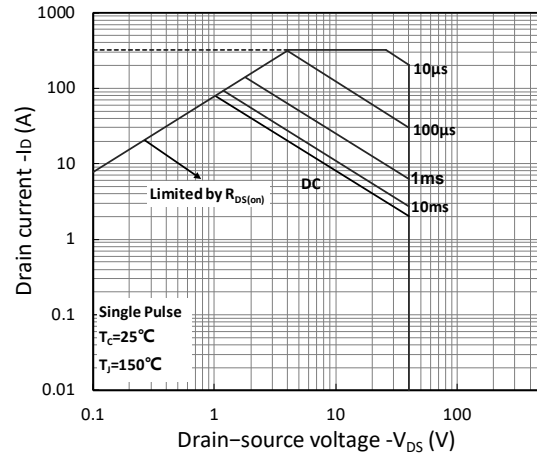


Figure 10. Safe Operating Area

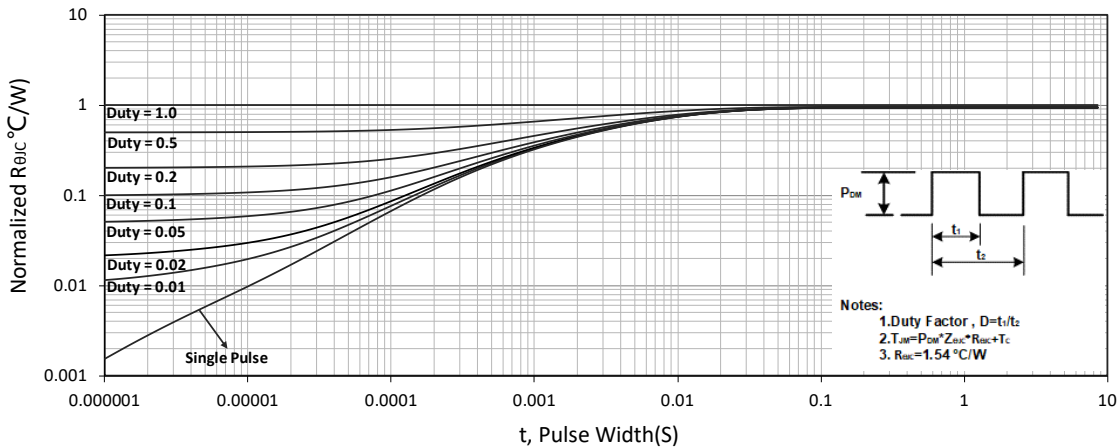
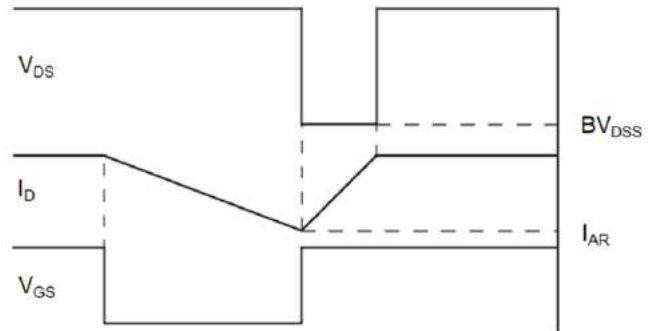
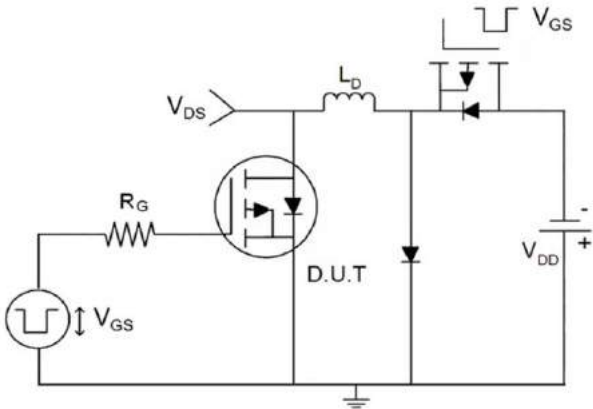


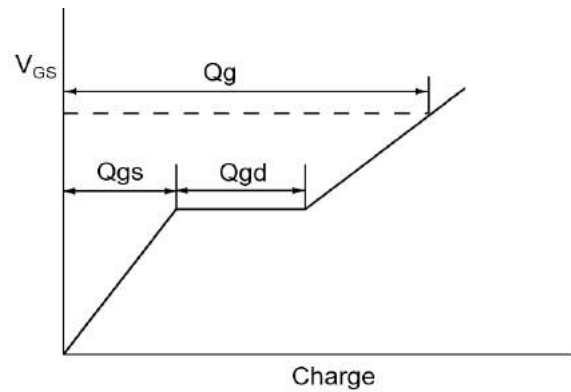
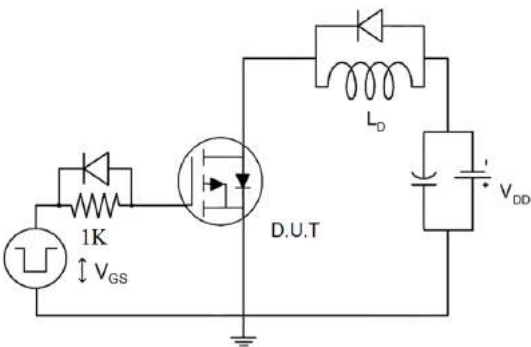
Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

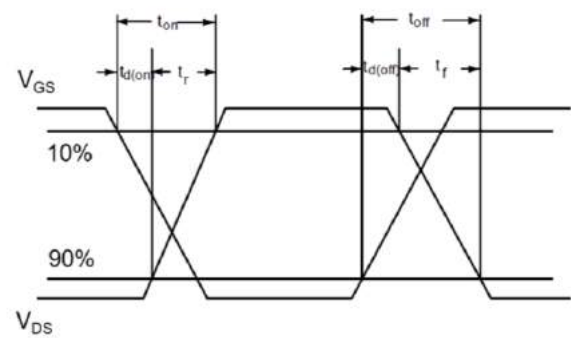
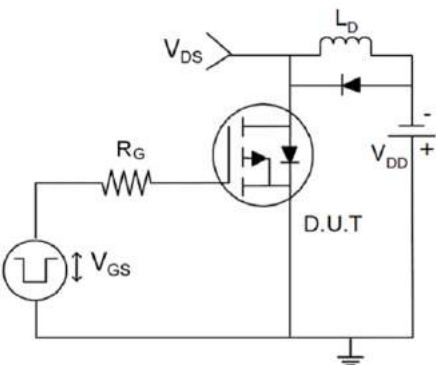
1) E_{AS} Test Circuits



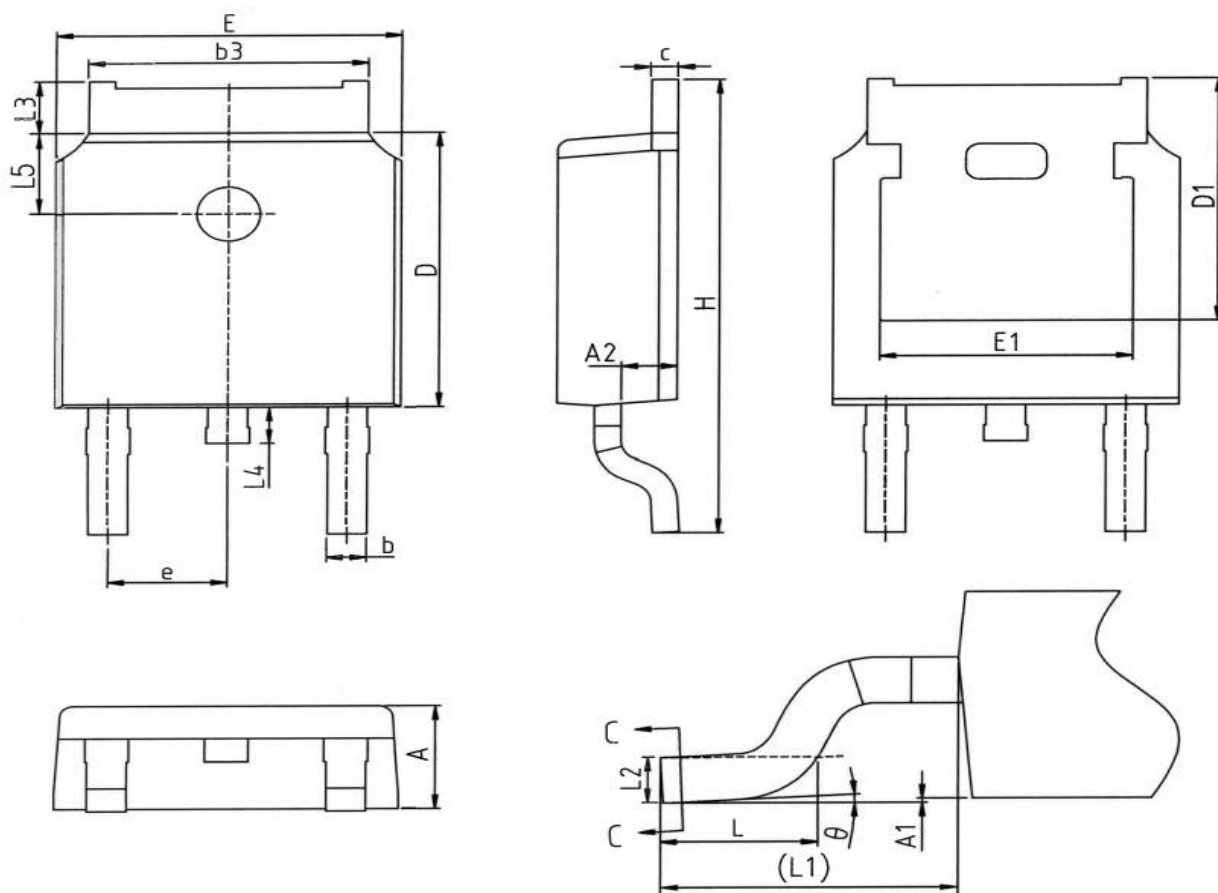
2) Gate Charge Test Circuit



3) Switch Time Test Circuit



TO-252 Package Information



SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.38
A1	0.00	-	0.12
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
θ	0°	-	8°

Customer Service

Sales and Service:

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